Silicon P Channel Power MOS FET Power Switching

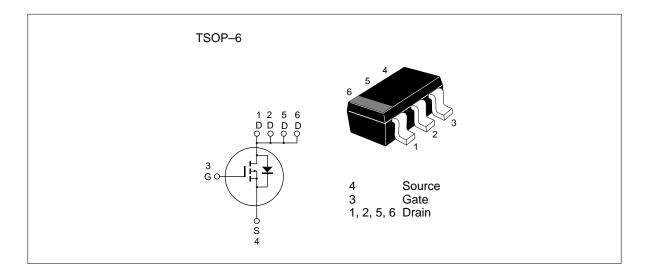
HITACHI

ADE-208-753C(Z) Preliminary, 4th. Edition Dec. 1, 1998

Features

- Low on-resistance
- Low drive current
- High density mounting
- 4.5V gate drive device can be driven from 5V source

Outline



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	-30	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D *2	-4.5	A
Drain peak current	I _{D(pulse)} *1	-18	A
Body-drain diode reverse drain current	*2	-4.5	A
Channel dissipation	Pch _(pulse) *2	2.0	W
	Pch _(continuous) *3	1.05	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

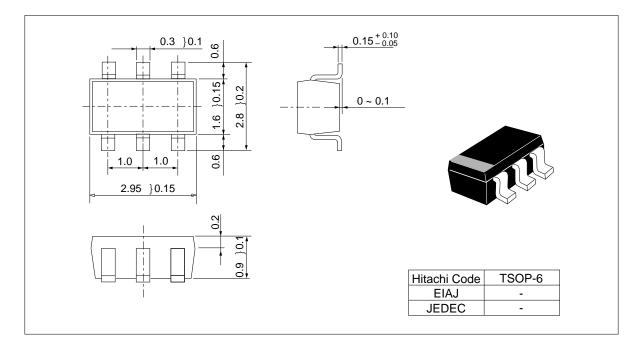
- 2. When using the alumina ceramic board (50 x 50 x 0.7 mm), PW \leq 5s,Ta=25°C
- 3. When using the alumina ceramic board (50 x 50 x 0.7 mm) , $Ta=25^{\circ}C$

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-30	_		V	$I_{D} = 10 \text{mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.5	V	$V_{DS} = -10V, I_{D} = -1mA$
Static drain to source on state	R _{DS(on)}	_	50	60	mΩ	$I_D = -3A, V_{GS} = -10V^{*1}$
resistance	$R_{\scriptscriptstyle DS(on)}$	_	80	105	$m\Omega$	$I_D = -3A, V_{GS} = -4.5V^{*1}$
Forward transfer admittance	y _{fs}	3	5.5	_	S	$I_D = -3A, V_{DS} = -10V^{*1}$
Input capacitance	Ciss	_	600	_	pF	$V_{DS} = -10V$
Output capacitance	Coss	_	220	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	150	_	pF	f = 1MHz
Turn-on delay time	$t_{\text{d(on)}}$	_	12	_	ns	$V_{GS} = -10V, I_{D} = -3A$
Rise time	t _r	_	85	_	ns	$R_L = 3.3\Omega$
Turn-off delay time	$t_{\text{d(off)}}$	_	55	_	ns	
Fall time	t_{f}	_	55	_	ns	
Body-drain diode forward voltage	V_{DF}		-0.95		V	$IF = -4.5A, V_{GS} = 0 *1$
Body-drain diode reverse recovery time	t _{rr}		50	_	ns	IF = -4.5A, $V_{GS} = 0$ diF/ dt =-20A/ μ s
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Note: 1. Pulse test

Package Dimensions (Unit: mm)



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